

The new SIPLACE TX micron

MAXIMUM ACCURACY FOR ADVANCED PRODUCTION



The high density system-in-package, IoT modules, wearables and submodules require highest accuracy in a high volume production environment.

The SIPLACE TX micron platform is developed to achieve best in class accuracy and to maximise the highest volume production in a compact and highly scalable placement machine.



The increasing demand for the mobility and connected world of the future requires a combination of high accuracy, higher throughput and the ability to handle fragile components in a compact placement platform.

The new innovative SIPLACE TX micron meets the requirements of electronics assembly industry and packaging industry.

With many new features like the high resolution glass scales and glass ceramics fiducials for gantry movement and “Touchless Placement” mode for the accurate process control for placement onto flux, paste or epoxy, the SIPLACE TX micron achieves new benchmarks in placement performance and productivity per area.

Key benefits at a glance:

- Up to 78,000 cph (Benchmark) for higher throughput and floorspace performance
- Better accuracy (up to $15\mu\text{m}$ @ 3σ) for placing high density boards and advanced packaging applications
- Selectable accuracy for individual components to place each component at the required accuracy with minimum impact on the throughput
- Programmable Low placement force (0.5N) and even “Touchless Placement” mode for fragile or sensitive components
- Centralised placement program creation and management allows easy recipe download to placement machine
- Innovative SIPLACE Software portfolio to support the productivity and operational efficiency of your production

SIPLACE TX micron

High Accuracy Package

High resolution glass scales

SIPLACE SpeedStar CP20 M2, with high resolution scales

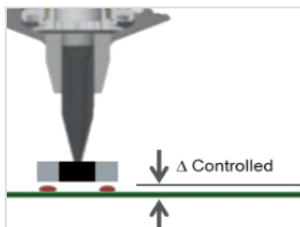


Additional fiducial bar – Y direction (15µm only)

Low expansion glass fiducial bar – X direction

„Touchless Placement“ - New and unique to SIPLACE

Fragile components such as dies can be precisely and controllably placed with the SIPLACE SpeedStar CP20 placement heads using a placement force of a mere 0 N.



Just 2 heads to meet the requirements for your module assembly

The **SIPLACE Speedstar**, as high speed Collect&Place head, combines handling of components sizes as small as 0201 (metric) with extremely high placement performance and accuracy.

The **SIPLACE MultiStar**, with its unique combination of three different placement modes, covers a very wide component range.



SIPLACE TX micron	
Placement speed (benchmark)	up to 78,000 cph
Placement accuracy @ 3 sigma	up to 20µm
PCB Dimensions (l x w)	Dual: 50mm x 45mm to 375mm x 260mm Single: 50mm x 45mm to 375mm x 430mm
Machine Dimensions (L x W x H)	1.00m x 2.23m x 1.45m
Feeder slots	Up to 80 x 8mm, Jedec Tray
Typical power consumption	1.9 kW
Air consumption	120 NI/min (2 x SIPLACE Speedstar)
Certifications	Semi S2/S8, Clean room class ISO 7

Available placement heads

Placement heads	SIPLACE SpeedStar	SIPLACE MultiStar
Placement speed (benchmark)	39,000 cph	24,000 cph
Component range	0.12 x 0.12 mm to 6 x 6 mm	0.11 x 0.11 mm to 15 x 15 mm
min. Lead pitch	80 µm	120 µm
min. Lead width	30 µm	50 µm
min. Ball pitch	100 µm	140 µm
min. Ball diameter	50 µm	70 µm

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